SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING THE SAME, AND ELECTRONIC APPARATUS

ABSTRACT OF THE DISCLOSURE

In a semiconductor device constituted by a film circuit, a semiconductor element, a reinforcement plate adhered to the film circuit, for surrounding this semiconductor element, and also a heat sink adhered to this reinforcement plate, which are sealed by employing resin, a stray capacitance between power supply terminals (between power supply and ground) is increased so as to increase the noise withstanding characteristic. Both the reinforcement plate and the heat sink own conductivity characteristics, a wiring film on the ground side among wiring films of the film circuit is electrically connected to one of the reinforcement plate and the heat sink, and a wiring film on the power supply side among these wiring films is electrically connected to the other of these reinforcement plate and heat sink. The heat sink is connected to the wiring film via, for instance, a conductive ring.

Figure 5C